**Product / Process Change Notice**

 **Parts Affected:**

Diodes and transistors manufactured in the SOT-26 case.

**Extent of Change:**

Change in assembly site; and change in die attach method from eutectic to silver epoxy.

**Reason for Change:**

As part of Central Semiconductor’s supply chain risk mitigation initiative, and in an effort to ensure an undisrupted supply of product, a change in assembly site is being made for the referenced products. Device specifications, quality, and reliability are not impacted by this change.

**Effect of Change:**

This change does not affect the fit, form or function of the devices.

**Qualification:**

|  |  |  |  |
| --- | --- | --- | --- |
| **Test** | **Condition** | **Duration** | **Failure rate** |
| **Temperature Cycling (T.C.)** | TA= -55°C to +175°C Dwell time = 15 min.**JESD22-A104 &** **MIL-STD-750 TM1051** | 1000 Cycles | 0/77 |
| **High Temp. Storage Life (H.T.S.L.)** | TA= +150℃ (-0/+10°C)**JESD22-A103** | 1000 Hours | 0/77 |
| **High Temp. Reverse Bias (H.T.R.B.)** | T=+125℃Bias conditions per Data Sheet **JESD22-A108** | 1000 Hours | 0/77  |
| **Unbiased Highly Accelerated Temp. and Humidity Stress Test (U.H.A.S.T.)** | T=+110℃, RH=85%**JESD22-A110** | 264 Hours | 0/77  |
| **Highly Accelerated Temp. and Humidity Stress Test (H.A.S.T.)** | T=+110℃, RH=85%**JESD22-A110** | 264 Hours | 0/77  |
| **Resistance to Solder Heat (R.S.H.)** | Pb free: T =270°C ±5°C, Dwell=7s +2/-0Thru-hole devices submerge to case**JESD22-B106** | 1 Cycle | 0/5  |
| **Thermal Shock Test (T.S.T.)** | T=-65℃ to +150°CDwell time = 5 min.Max Transfer time 20 sec. **JESD22-A106**  |  100 Cycles | 0/77  |
| **Solderability (SD)**  | Steam Age: T=93°C +3/-5°C.Pb-free Dip: T=245°C +/-5°CDwell time = 5+/-0.5sec**MIL-STD-750 TM2026** | 1 Cycle | 0/15  |

**Effective Date of Change:**

Existing inventory will be shipped until depleted.

**Sample Availability:**

Please contact your salesperson or manufacturer’s representative for samples.

**Part Numbers Affected:**

|  |  |
| --- | --- |
| CMXD2004 | CMXSH-3 |
| CMXD2004S | CMXTC935A |
| CMXD2004SR | CMXT2222A |
| CMXD2004TO | CMXT3904 |
| CMXD3003TO | CMXT3906 |
| CMXD3004SR | CMXT3946 |
| CMXD4448 | CMXZ10VTO |
| CMXD6001 |   |

As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor’s Product/Process Change Notification (PCN).

|  |  |
| --- | --- |
| Company Name: |  |
| Address: |  |
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|  |
| Printed Name: |  |
| Title: |  |
| Signature: |  |
| Date: |  |